AMENDMENTS TO THE SPECIFICATION

1. Please substitute the paragraph [0006] on pages 1-2 with the following amended paragraph:

In addition, the organic layer 16 further includes a hole transport layer (HTL) 20, an emitting layer (EML) 22, and an electron transport layer (ETL) 24 positioned on the transparent conductive layer 14, respectively. Furthermore, a hole injection layer (HIL, not shown in Fig.1) can be positioned between the transparent conductive layer 14 and the HTL 20, and an electron injection layer (EIL, not shown in Fig.1) can be formed between the metal layer 18 and the ETL 24, for improving an adhesion problem of the transparent conductive layer 14, the organic layer 16, and the metal layer 18, and benefiting electrons and holes being injected into the organic layer 16. Moreover, another emitting layer (not shown in Fig.1) that has an ability of transporting the electrons, or another HTL (not shown in Fig.1) that has an ability of irradiating light, can be chosen to simply structure of the OLED. Typically, the transparent conductive layer 14 is composed of indium tin oxide (ITO) or indium zinc oxide (IZO). The organic layer 16 is formed by utilizing a thermal evaporation process, the HTL 20 is composed of diamine chemical compound, and the metal layer 18 is composed of magnesium (Mg), aluminum (Al), lithium (Li) or an alloy of Mg, Al, and Li.

2. Please substitute the paragraph [0020] on pages 5-6 with the following amended paragraph:

Additionally, the passivation structure 60 of the present invention has an annular ditch, i.e. two ditches 74 as shown in Fig.2, positioned within the passivation structure 60 corresponding to substrate 52 and between the spot glue region and the predetermined region. If an excess of sealing material 62 is utilized on the spot glue region of the OLED 50 while performing the encapsulation process of the OLED 50, the excess sealing material 76 will flow into the ditches 74, and be not in touch with the organic layer 56 and affect normal operation of the OLED 50. In the preferred embodiment of the present invention, a cross-sectional view of each ditch 74 is substantially a rectangle, and a depth of each ditch 74 is less than half of a thickness of the passivation structure 60 to prevent from affecting mechanism strength of the passivation structure 60. However, the present invention is not limited in this, the cross-sectional view of each ditch 74 can be a polygon, U-shape, or can have various angles, to benefit the excess sealing material 76 flowing into the ditches 74, and numbers of the ditches 74 can be adjusted according to the demand of the OLED 50. Moreover, ditches ~~(not shown in Fig.2)~~ 73 similar to the ditches 74 can be positioned within the substrate 52 or the transparent conductive layer 54 between the spot glue region and the predetermined region, and the excess sealing material 76 can flow into the ditches 73 of the substrate 52 or the transparent conductive layer ~~74~~ 54 to prevent the organic layer 56 from contacting with the excess sealing material 76. In addition, a depth of each ditch 73 of the substrate 52 or the transparent conductive layer ~~74~~ 54 is less than half of a thickness of the

substrate 52 or the transparent conductive layer 54.

3. Please substitute the paragraph [0022] on pages 6-7 with the following amended paragraph:

Each device region A includes a conductive layer 84 positioned on the device region A, an organic layer 86 positioned on an active region of the device region A, and a metal layer 88 positioned on the organic layer 86. The conductive layer 84 is used as an anode of each OLED, and the metal layer 88 is used as a cathode of each OLED. In addition, the organic light emitting device 80 also includes a substrate functioning as a passivation structure 90 of the organic light emitting device 80 positioned parallel with the substrate 82. And that, a lower surface of the passivation structure 90 has at least two first regions C corresponding to the device regions A of the substrate 82, at least one second region D corresponding to the segmented region B of the substrate 82, and a plurality of ditches 92 positioned within each first region C of the passivation structure 90. Furthermore, a sealing material 94 is positioned on a spot glue region of the substrate 82 and outside each active region for binding the substrate 82 and the passivation structure 90 together. The ditches 92 are used to prevent the sealing material 94 from overflowing into the segmented region B and each active region of the substrate 82 and affecting normal operation of each OLED. As mentioned above, ditches ~~(not shown in Fig.3)~~ 91 similar to the ditches 92 can be positioned within the substrate 82 or the transparent conductive layer 84 between the spot glue

region and the predetermined region, and an excess sealing material 96 can flow into the ditches 91 of the substrate 82 or the transparent conductive layer 84 to prevent the organic layer 86 from contacting with the excess sealing material 96. In addition, a depth of each ditch 91 of the substrate 82 or the transparent conductive layer 84 is less than half of a thickness of the substrate 82 or the transparent conductive layer 84.

4. Please substitute the title of the invention with the following amended title:

ORGANIC LIGHT EMITTING DIODE INCLUDING DITCHES IN A SUBSTRATE